

Terrace 1		Corrosion Reliability of Electronic Materials and Devices
	<i>Chair(s)</i>	<i>H. Schweigart / M. Jellesen</i>
11:10	80371	Sabine Knapke (Robert Bosch GmbH, Reutlingen, Germany) / Katharina Schultz (Robert Bosch GmbH, Reutlingen, Germany) / Klaus Micheler (Robert Bosch GmbH, Reutlingen, Germany): <b>Electrochemical Corrosion and Thermal Effects in Electronic Systems</b>
11:30	79211	Elke Ludwig (TU Wien, Wien, Austria) / Paul Linhardt (TU Wien, Vienna, Austria) / Maximilian Bonta (TU Wien, Vienna, Austria) / Andreas Limbeck (TU Wien, Vienna, Austria) / Johannes Frank (TU Wien, Vienna, Austria) / Silvia Larissegger (KAI, Villach, Austria) / Michael Nelhiebel (KAI, Villach, Austria): <b>Corrosion of Copper in Combination with Polyimide</b>
11:50	98145	Kamila Piotrowska (Technical University of Denmark, Lyngby, Denmark) / Morten Stendahl Jellesen (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): <b>The influence of solder mask and hygroscopic flux residues on water layer formation on PCBA surface and corrosion reliability of electronics</b>
12:10	96852	Jesper Konge (Grundfos A/S, Bjerringbro, Denmark): <b>A strategic approach to Electronics Corrosion Reliability</b>
12:30		Lunch
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	<i>Chair(s)</i>	<i>M. Bálint / R. Ambat</i>
14:00	80611	Sabine Reither (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Maximilian Bonta (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Silvia Larissegger (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Michael Nelhiebel (Kompetenzzentrum Automobil- und Industrieelektronik GmbH, Villach, Austria) / Andreas Limbeck (TU Wien, Wien, Austria) / Günter Fafilek (TU Wien, Wien, Austria): <b>Electrochemical characterization of copper films and comparison of strategies for corrosion protection</b>
14:20	87386	Helmut Schweigart (Dr. O.K. Wack Chemie GmbH, Ingolstadt, Donau, Germany): <b>Fast and Cost-Effective Coating Quality Test</b>
14:40	83451	Vadimas Verdingovas (Technical University of Denmark, Kgs. Lyngby, Denmark) / Morten Jellesen (Technical University of Denmark, Kgs. Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Kgs. Lyngby, Denmark): <b>Critical level of water layer formation on PCBA and sequential failure</b>
15:00	81676	Bálint Medgyes (Budapest University of Technology and Economics, Budapest, Hungary) / Gábor Harsányi (Budapest University of Technology and Economics, Budapest, Hungary) / László Gál (Budapest University of Technology and Economics, Budapest, Hungary): <b>Electrochemical migration of Ni and ENIG surfaces finishes in different Na<sub>2</sub>SO<sub>4</sub> solutions using THB Tests</b>
15:20	79376	Aliakbar Khanghali (Vrije Universiteit Brussel, Belgium) / Tom Hauffman (Vrije Universiteit Brussel, Belgium) / Eva Rogge (Europlasma, Oudenaarde, Belgium) / Samir Loulidi (Europlasma, Oudenaarde, Belgium) / Iris De Graeve (Vrije Universiteit Brussel, Belgium): <b>Study of plasma polymer films for the corrosion protection of Printed Circuit Boards</b>
15:40		Coffee Break
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16:10	72626	Hiroyuki Abe (Hitachi Automotive Systems, Ltd., Ibaraki-ken, Japan) / Akio Yasukawa (Hitachi Automotive Systems, Ltd., Ibaraki-ken, Japan) / Rintaro Minamitani (Hitachi, Ltd., Research & Development Group, Ibaraki-ken, Japan) / Hiroyuki Saito (Tokyo Denki University, Tokyo, Japan): <b>Corrosion life prediction of electronic module mounted in engine room by SO<sub>2</sub> gas released from rubber duct</b>
16:30	73347	Tung Han Chuang (National Taiwan University, Taipei, Taiwan) / Yan Cheng Lin (National Taiwan University, Taipei, Taiwan) / Chun-Hao Chen (National Taiwan University, Taipei, Taiwan) / Chih-Hsin Tsai (Wire Technology Co., Taichung, Taiwan) / Shang-Chih Wang (Wire Technology Co., Taichung, Taiwan) / Hsing-Hua Tsai (Wire Technology Co., Taichung, Taiwan): <b>Corrosion and Ion Migration of Ag-alloy Bonding Wires with various Pd and Au Contents</b>
16:50	81251	Abhijeet Yadav (Technical University of Denmark, Lyngby, Denmark) / Visweswara Chakravarthy Gudla (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): <b>Corrosion Reliability of Low Power Electrical Contacts</b>
17:10	87216	Kirsten Weide-Zaage (Leibniz Universität Hannover, Hannover, Germany) / Helene Fremont (University of Bordeaux IMS laboratory UMR-5218, Bordeaux, France) / Alexandrine Guédon-Gracia (IMS laboratory UMR-5218, University of Bordeaux, Bordeaux, France) / Yuan Feng (RESRI Group, Leibniz Universität Hannover, Hannover, Germany) / Amin Chen (LUH IMS-RESRI, Hannover, Germany): <b>Study of Corrosion in BGA Solder Balls</b>
17:30		TF MEETING
19:00		Congress Dinner

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10:10	95962	Morten Stendahl Jellesen (Technical University of Denmark, Kongens Lyngby, Denmark) / Vadimas Verdingovas (DTU, Lyngby, Denmark) / Rajan Ambat (DTU, Lyngby, Denmark): <b>Corrosion investigations of a voltage biased printed circuit board assembly under high humidity conditions</b>
10:30	97435	Célia Aparecida Lino dos Santos (Laboratory for Corrosion and Protection, São Paulo, Brazil) / Zehbour Panossian (Laboratory for Corrosion and Protection, São Paulo, Brazil): <b>The current stage of TR-Fe-B permanent magnet protection against corrosion</b>
10:50	87396	Kim Albert Schmidt (FORCE Technology, Horsholm, Denmark) / Anders Bonde Kentved (FORCE Technology, Horsholm, Denmark): <b>Method for practical characterization of humidity ingress in electronic enclosures</b>
11:10	81106	Xiankang Zhong (Southwest Petroleum University, Chengdu, China): <b>The role of precipitates in the electrochemical migration of Sn and Cu</b>

Forum Hall Foyer		Corrosion Reliability of Electronic Materials and Devices
P-20-214	98957	Liao Bokai (Huazhong University of Science and Technology Wuhan, China PR) / Shuai Hu (Huazhong University of Science and Technology Wuhan, China PR) / Lisha Wei (Huazhong University of Science and Technology Wuhan, China PR) / Hongyu Cen (Huazhong University of Science and Technology Wuhan, China PR) / Zhenyu Chen (Huazhong University of Science and Technology Wuhan, China PR) / Xingpeng Guo (Huazhong University of Science and Technology Wuhan, China PR): <b>Effect of solder flux residue weak organic acids on electrochemical migration of tin in thin electrolyte layer</b>
P-20-215	98245	Feng Li (Technical University of Denmark, Lyngby, Denmark) / Vadimas Verdingovas (Technical University of Denmark, Lyngby, Denmark) / Bálint Medgyes (Budapest University of Technology and Economics, Budapest, Hungary) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): <b>Corrosion reliability of lead-free solder systems used in electronics</b>
P-20-216	96797	Dusan Majtas (Masaryk University, Brno, Czech Republic) / Katerina Kreislova (SVUOM Ltd., Prague, Czech Republic) / Libor Turek (SVUOM Ltd., Prague, Czech Republic): <b>Failure of electric devices due to H<sub>2</sub>S</b>
P-20-217	86311	Abhijeet Yadav (Technical University of Denmark, Lyngby, Denmark) / Shruti Bargaonkar (Technical University of Denmark, Lyngby, Denmark) / Kamila Piotrowska (Technical University of Denmark, Lyngby, Denmark) / Morten Stendahl Jellesen (Technical University of Denmark, Lyngby, Denmark) / Rajan Ambat (Technical University of Denmark, Lyngby, Denmark): <b>The effect of reflow solder paste on corrosion reliability in electronics under humid conditions</b>